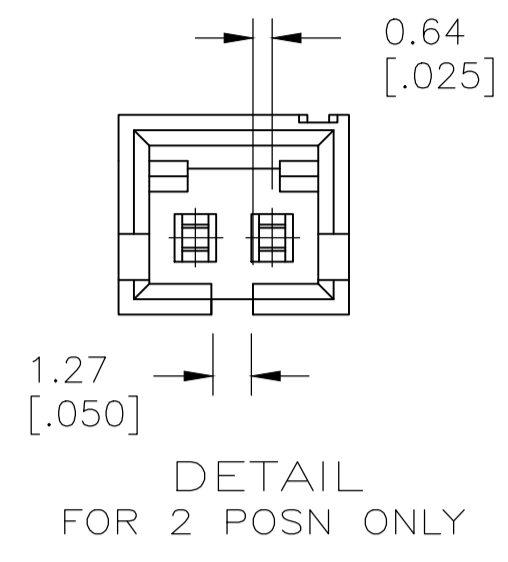
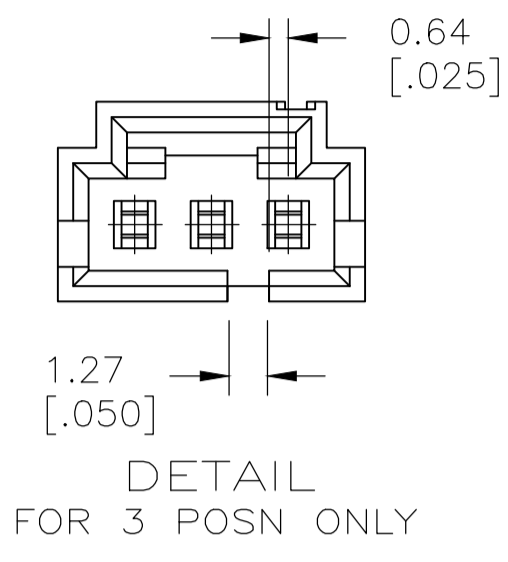
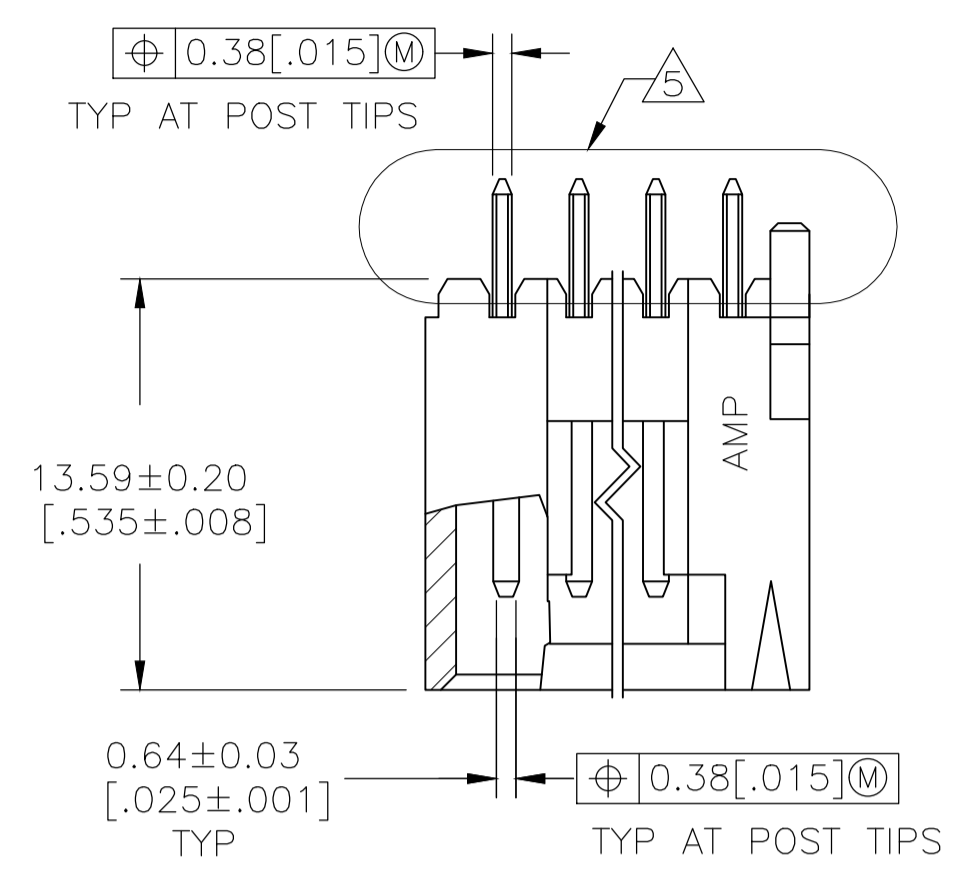
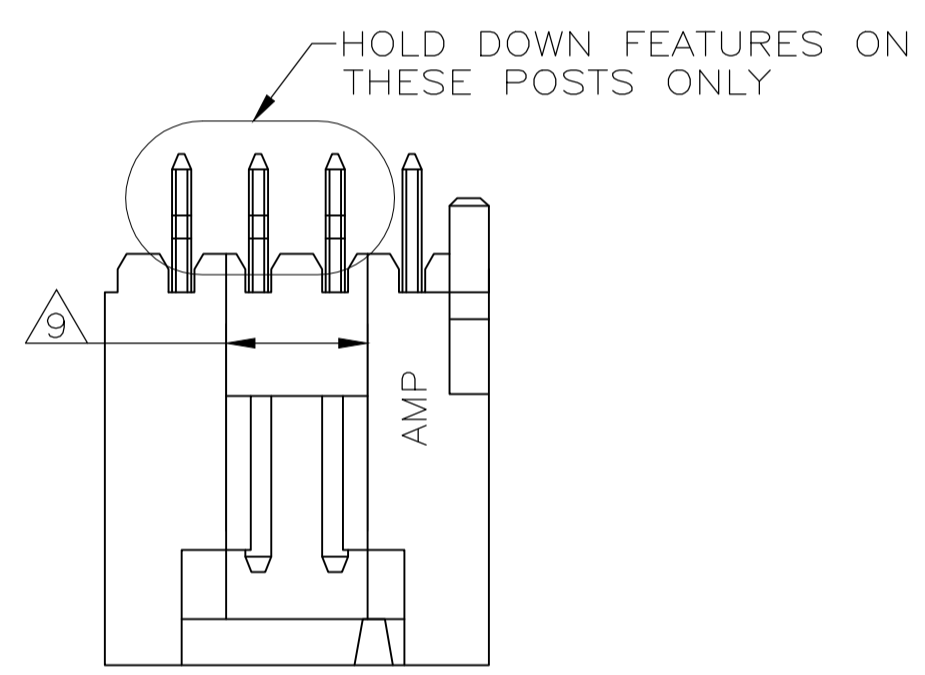
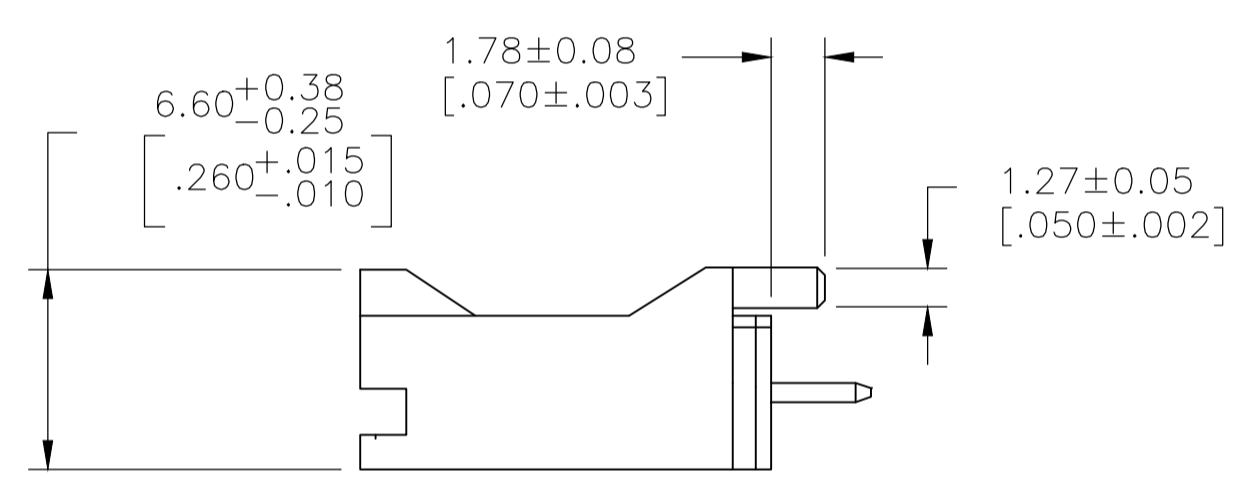
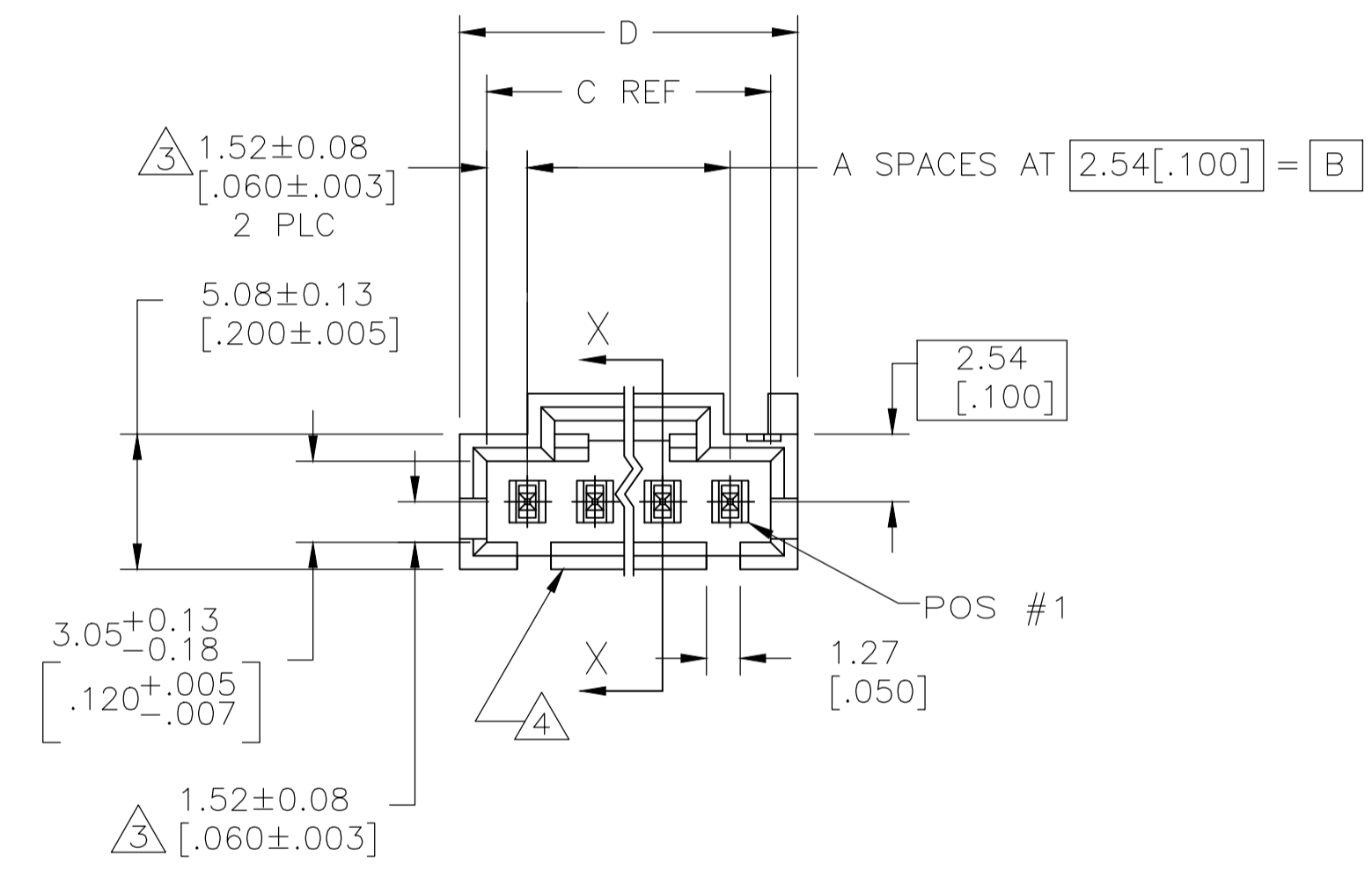


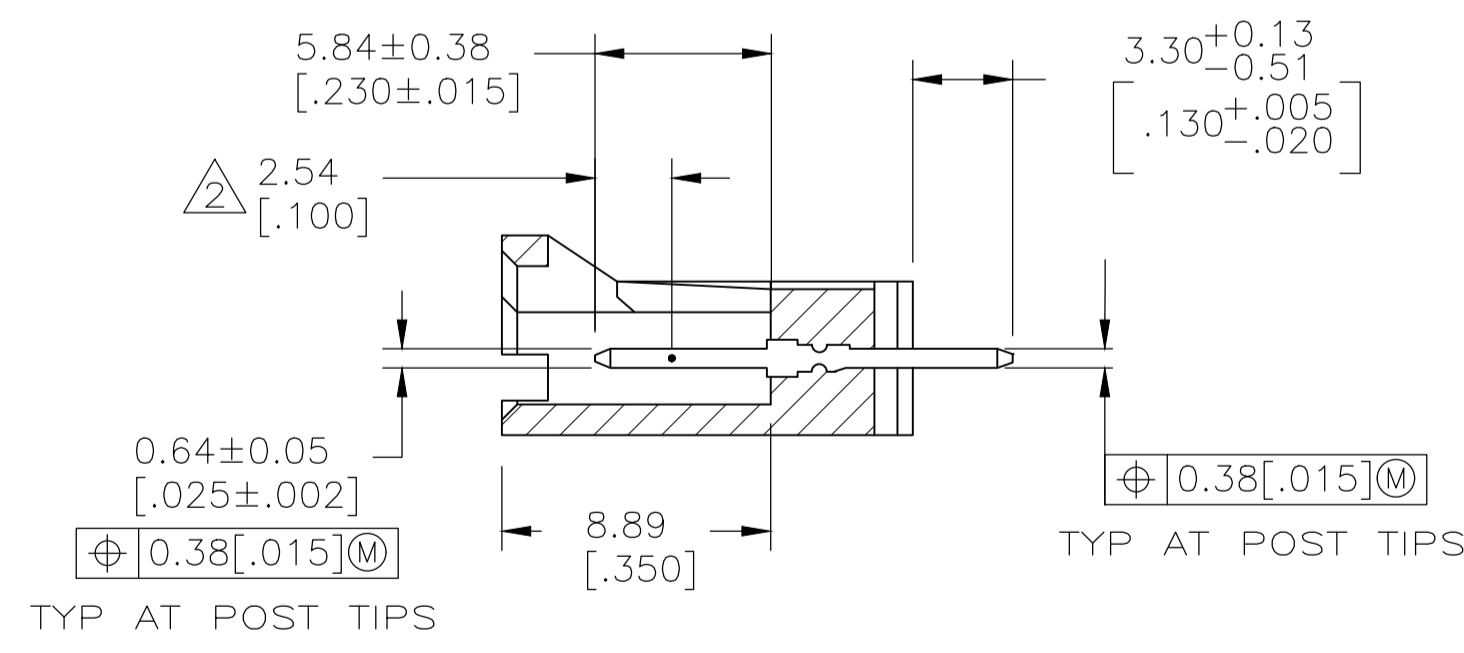
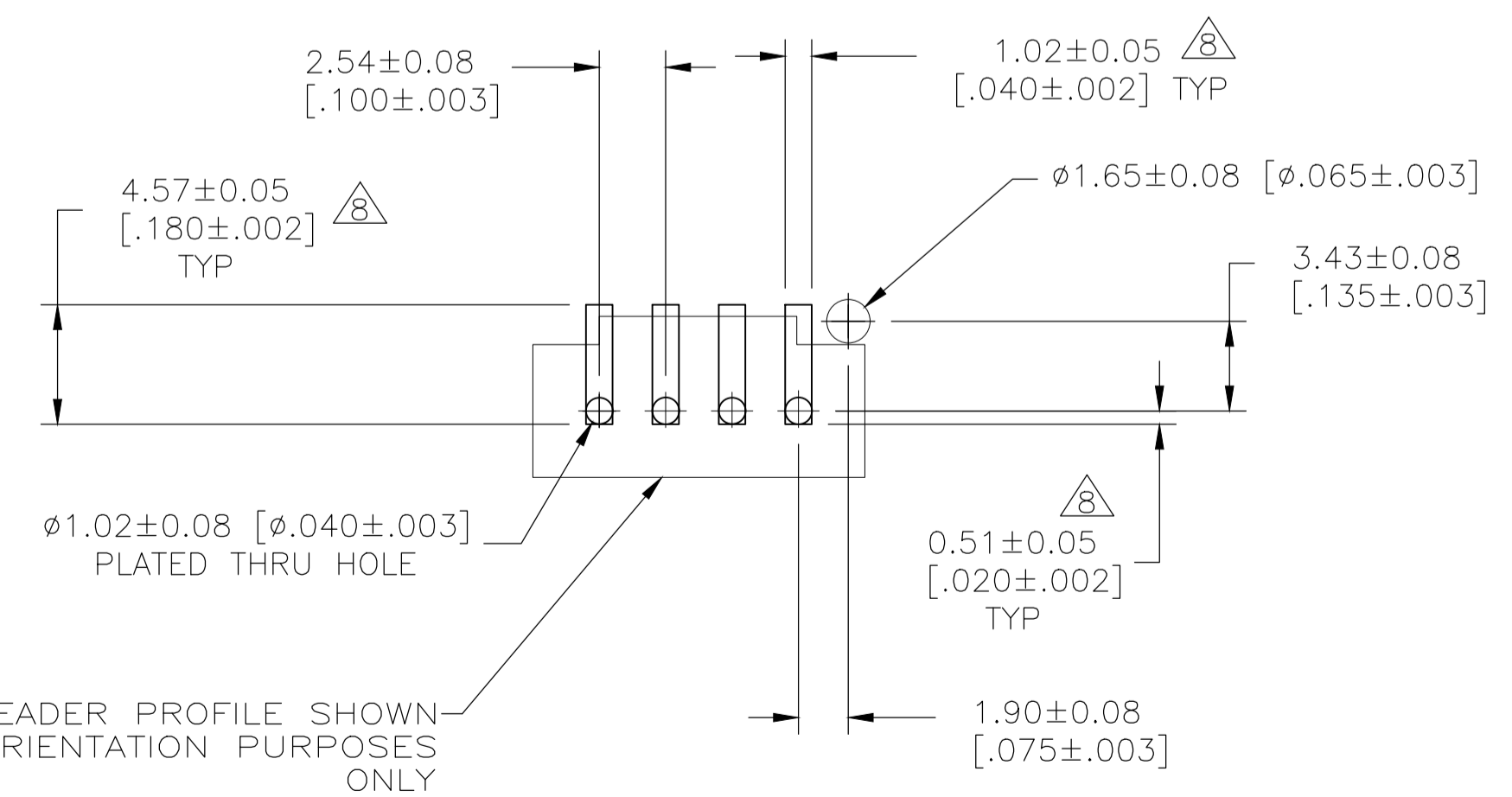
REVISIONS					
P	LTR	DESCRIPTION	DATE	DMN	APVD
A		REVISED PER ECO-20-001912	03JUN2020	SB	JO



- ① 0.00254-0.00508 [.000100-.000200] TIN OVER
0.00127 [.000050] NICKEL.
- ② POINT OF MEASUREMENT FOR PLATING THICKNESS
- ③ THESE DIMENSIONS APPLY WHERE THE POST INTERSECTS THE HOUSING
- ④ ON ASSEMBLIES WITH FOUR OR MORE POSITIONS, TWO POLARIZATION SLOTS.
- ⑤ SELECT POST TAILS FORMED TO PROVIDE CONNECTOR HOLD DOWN UNTIL SOLDERED (SEE DETAIL Z).
- ⑥ MATERIAL: HOUSING- HIGH TEMP THERMOPLASTIC, COLOR-SEE TABLE.
POSTS- BRASS.
- ⑦ PRELIMINARY PART - NOT RELEASED FOR PRODUCTION.
- ⑧ DIMENSIONS NOTED ARE FOR SOLDER STENCIL LAYOUT USE WITH 1.58±0.20[.062±.008] THICK PRINTED CIRCUIT BOARDS.
- ⑨ 0.25 [.010] RECESS PERMISSIBLE IN THIS AREA FOR MOLD SHUT OFF



HOLD DOWN CONFIGURATION FOR 4 POSITION ASSEMBLY ONLY



RECOMMENDED PC BOARD MOUNTING DIMENSIONS
RECOMMENDED STENCIL THICKNESS = 0.25[.010]



D	C	B	A	NO OF POSN	ASSEMBLY PART NUMBER
15.24 [.600]	13.21 [.520]	10.16 [.400]	4	5	1571194-4
12.7 [.500]	10.67 [.420]	7.62 [.300]	3	4	1571194-3
10.16 [.400]	8.13 [.320]	5.08 [.200]	2	3	1571194-2
7.62 [.300]	5.59 [.220]	2.54 [.100]	1	2	1571194-1

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN R BROWN 02JAN02		TE Connectivity	
DIMENSIONS: mm [INCHES]		TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD J GEFSEFORD 02JAN02	
0 PLC	± -	APVD J GEFSEFORD 02JAN02		NAME	
1 PLC	± -	PRODUCT SPEC		HEADER ASSY, AMPMODU MTE, VERTICAL,	
2 PLC	± -	APPLICATION SPEC		WITH LATCH, SINGLE ROW, .100 CL, .025 SQ POSTS,	
3 PLC	± 0.38 [.005]	SIZE		108-25034	
4 PLC	± -	WEIGHT		PCB ORIENTATION, RETENTIVE POSTS, SPECIAL PLATING	
ANGLES	± -	CUSTOMER DRAWING		RESTRICTED TO	
MATERIAL SEE NOTE 6		FINISH SEE NOTE 1		SCALE 4:1 SHEET 1 OF 1 REV A	

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[TE Connectivity:](#)

[1571194-4](#)